

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6804xxxx4R-G  
Typical Mass: 4 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.377	Silicon	94400	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	1.255	Nickel	313900	7440-02-0
	0.116	Silver	29100	7440-22-4
	0.022	Gold	5600	7440-57-5
Die attach	0.026	Epoxy Resin	6600	—
	0.016	Acrylic Resin	3900	—
Bonding wire	0.060	Gold	15100	7440-57-5
Resin	1.649	Silica	412200	60676-86-0
	0.167	Epoxy Resin	41800	—
	0.157	Phenol Resin	39300	—
	0.153	Metal hydroxide	38200	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."